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Secondly, please refer to FIG. 5, which is a cross-sectional view showing the structure of an organic EL device in accordance with another embodiment of the present invention. As shown in the figure, the present embodiment is characterized in that moisture absorbers 662 implemented by using a material with moisture absorption properties are formed between the bottom insulating pads 362 and the heat sinks 372. The protective layer 42 does not necessarily fill in the device, so that there is space 64 formed between the organic layer 34, the second electrodes 38, the moisture absorbers 622 and the protective layer 42. Therefore, the moisture absorbers 622 absorb, from the organic layer 34 through the space 64, any residual moisture remaining from the fabrication process. The heat sinks are also improved in cooling efficiency by the flow of gas in the space 64. In the present embodiment, the moisture absorbers 622 do not contact the first electrodes 32, the organic layer 34 and the second electrodes 38; therefore, they can be formed by materials having moisture absorption properties, regardless of their insulating property. The bottom insulating pads 362 can also be made of general insulating materials. Accordingly, the present embodiment provides a wide range for material selection and ease in fabrication.

MARKED VERSION of the Amended Specification Paragraph:

Secondly, please refer to FIG. 5, which is a cross-sectional view showing the structure of an organic EL device in accordance with another embodiment of the present invention. As shown in the figure, the present embodiment is characterized in that moisture absorbers 662 implemented by using a material with moisture absorption ~~function~~ properties are formed between the bottom insulating pads 362 and the heat sinks 372. The protective layer ~~46~~ 42 does not necessarily fill in the device, so that there is space 64 formed between the organic layer 34, the second electrodes 38, the moisture absorbers 622 and the protective layer ~~46~~ 42. Therefore, the moisture absorbers 622 absorb, from the organic layer 34 through the space ~~46~~ 64, ~~the any~~ residual moisture remaining from the ~~unable to eliminate during~~ fabrication process. The heat sinks are also improved in the cooling efficiency ~~with the help from~~ by the flowing of gas in the space ~~46~~ 64. In the present embodiment, the moisture absorbers 622 do not contact the first electrodes 32, the organic layer 34 and the second electrodes 38; therefore, they can be formed by materials ~~with~~ having moisture absorption properties ~~function~~, regardless of their insulating property. The bottom insulating pads 362 can also be made of general insulating materials. Accordingly, the present embodiment provides a wide range for material selection and ease in fabrication.